ABSTRACT OF DISCLOSURE

INTEGRATED VCSELs ON TRADITIONAL VLSI PACKAGING

A circuit module including at least one Application Specific Integrated Circuit (ASIC) **504** and a plurality of Vertical Cavity Surface-Emitting Laser (VCSEL) array modules **522** is built using a standard ceramic or organic VLSI package substrate **500**, resulting is a high density device with a small footprint. Interconnection between the electronic devices and the VCSEL array modules is accomplished using standard integrated circuit packaging technology and flexible connectors **518**. Optical connections from the VCSEL arrays to fiber optic cables are made possible by integrating industry-standard optical connectors onto the package. Optical receiver and transceiver modules may also be incorporated into the circuit module.

(FIG. 7)